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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HARTMUT RUELKE
JOERG HOHAGE
THOMAS WERNER
MICHAEL KIENE

Examiner: Thanhha S. Pham

Group Art Unit: 2813

Att'y Docket: 2000.108700/DE0363

Customer No.: 23720

Serial No.: 10/716,681


Filed: November 19, 2003

For: NITROGEN-ENRICHED LOW-K
BARRIER LAYER FOR A COPPER
METALLIZATION LAYER

RESPONSE TO OFFICE ACTION DATED JUNE 22, 2005

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:	
September 21, 2005 Date	 Signature

This paper is submitted in response to the Office Action dated June 22, 2005, for which the three-month date for response is September 22, 2005.

No fees are believed to be due in connection with the present paper. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from the Advanced Micro Devices, Inc. Deposit Account No. 01-0365/DE0363.¹

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.

¹ In the event the monies in that account are insufficient, the Director is authorized to withdraw funds from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/108700.